

<<微机电系统基础>>

图书基本信息

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内容概要

本书全面论述了微机电系统（MEMS）的基础知识，涵盖了MEMS技术的主要方面，同时引用了经典的MEMS研究论文和前沿的技术论文，为学生深入学习MEMS技术提供了指引。书中提炼出了四个典型的传感器实例：惯性传感器、压力传感器、流量传感器和触觉传感器，并介绍了利用不同原理、材料和工艺制造这些传感器的方法，既便于比较，又可以启发学生的创新意识并提高创新能力。本书被美国斯坦福大学、伊利诺伊大学等选为教材。

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他领导的西北大学MED x 实验室主要的科研方向为传感器、仿生传感器、微机电系统和纳米加工技术、流体传感器、触觉传感器及各种传感器的应用。

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